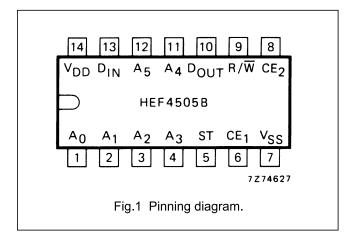
HEF4505B LSI

#### **DESCRIPTION**

The HEF4505B is a 64-bit, 1-bit per word, fully decoded and completely static, random access memory. The memory is strobed for reading or writing only when the strobe input (ST), chip enable inputs (CE $_1$  and CE $_2$ ) are HIGH simultaneously. The output data is available at the data output (D $_{\rm OUT}$ ) only when the memory is strobed, the read/write input (R/W) is HIGH and after the read access time has passed. Note that the three-state output is initially disabled and always goes to the LOW state before data is valid. The output is disabled in the high-impedance OFF-state, when the memory is not strobed or R/W is LOW. R/W may remain HIGH during a read cycle or LOW during a write cycle. The output data has the same polarity as the input data.



HEF4505BP(N): 14-lead DIL; plastic

(SOT27-1)

HEF4505BD(F): 14-lead DIL; ceramic (cerdip)

(SOT73)

(): Package Designator North America

### **PINNING**

$A_0$ to $A_5$	address inputs
CE <sub>1</sub> , CE <sub>2</sub>	chip enable inputs
$R/\overline{W}$	read/write input
ST	strobe input
D <sub>IN</sub>	data input
D <sub>OUT</sub>	data output

### **FUNCTION TABLE**

ST, CE <sub>1</sub> , CE <sub>2</sub>	R/W	D <sub>OUT</sub>	MODE
L	L	Z	disabled
Н	L	Z	write
L	Н	Z	disabled
Н	Н	equal to memory data	read

### Note

1. H = HIGH state (the more positive voltage)

L = LOW state (the less positive voltage)

Z = high-impedance OFF-state

### **SUPPLY VOLTAGE**

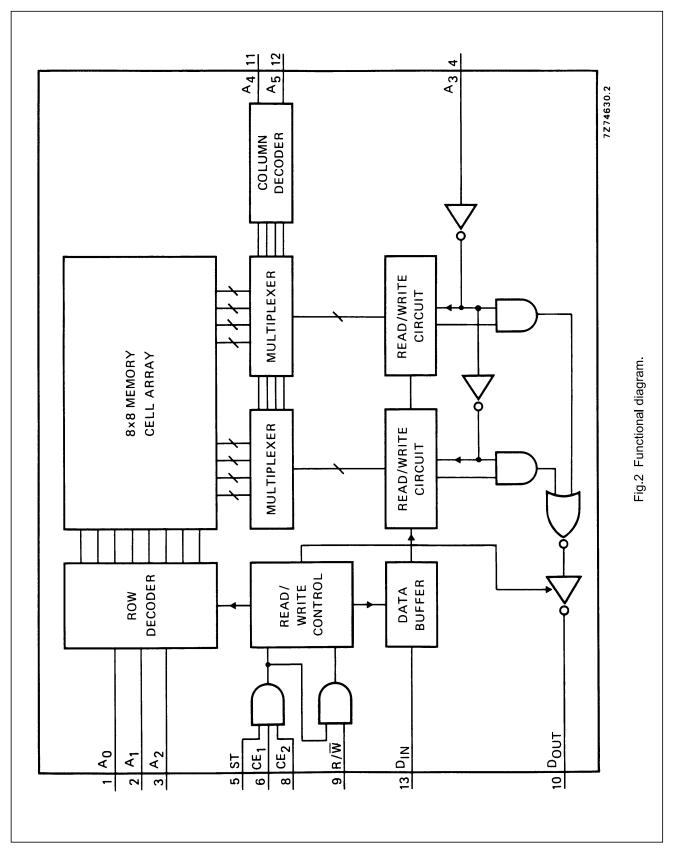
RATING	OPERATING			
–0,5 to +15	4,5 to 15 V			

### Note

1. Minimum standby voltage for data retention is 3 V.

### FAMILY DATA, IDD LIMITS category LSI

See Family Specifications



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### **AC CHARACTERISTICS**

 $V_{SS}$  = 0 V;  $T_{amb}$  = 25 °C;  $C_L$  = 50 pF; input transition times  $\leq 20~ns$ 

	V <sub>DD</sub>	SYMBOL	MIN.	TYP.	MAX.		TYPICAL EXTRAPOLATION FORMULA
Minimum strobe pulse	5		75	35		ns	
width; LOW	10	t <sub>STL</sub>	45	22		ns	
	15		30	15		ns	
	5			350	700	ns	
Read cycle time	10	t <sub>RC</sub>		250	500	ns	
	15			210	420	ns	
	5			220	440	ns	
Write cycle time	10	t <sub>WC</sub>		125	250	ns	
	15			75	150	ns	
	5			330	660	ns	303 ns + (0,55 ns/pF) C <sub>L</sub>
Read access time	10	t <sub>ACC</sub>		135	270	ns	124 ns + (0,23 ns/pF) C <sub>L</sub>
	15			100	200	ns	92 ns + (0,16 ns/pF) C <sub>L</sub>
	5		80	40		ns	
Address recovery time	10	t <sub>AR</sub>	40	20		ns	
	15		25	10		ns	
	5		180	90		ns	
Read recovery time	10	t <sub>RR</sub>	120	60		ns	
·	15		90	45		ns	
	5		75	35		ns	
Write recovery time	10	t <sub>WR</sub>	45	25		ns	
	15		40	20		ns	
3-state propagation delays							
	5			105	210	ns	
Output disable times	10	t <sub>PHZ</sub> ,		60	125	ns	
	15	t <sub>PLZ</sub>		55	115	ns	
Set-up times	5		-20	-40		ns	
$A_n \rightarrow ST$	10	t <sub>suA</sub>	_10	-20		ns	
	15		<b>-</b> 5	-10		ns	
	5		-30	-60		ns	
$R/\overline{W} \rightarrow ST$	10	t <sub>suR</sub>	_15	-30		ns	
	15		_5	-10		ns	
	5		160	80		ns	
$D_IN  o ST$	10	t <sub>suD</sub>	75	35		ns	
	15		45	20		ns	
	5		240	120		ns	
$R/\overline{W} \rightarrow ST$	10	$t_{suW}$	100	50		ns	
	15		75	35		ns	

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	V <sub>DD</sub>	SYMBOL	MIN.	TYP.	MAX.	TYPICAL EXTRAPOLATION FORMULA
Hold time	5		-20	-40	ns	
$D_{IN} \rightarrow ST$	10	t <sub>holdD</sub>	5	-10	ns	
	15		10	0	ns	

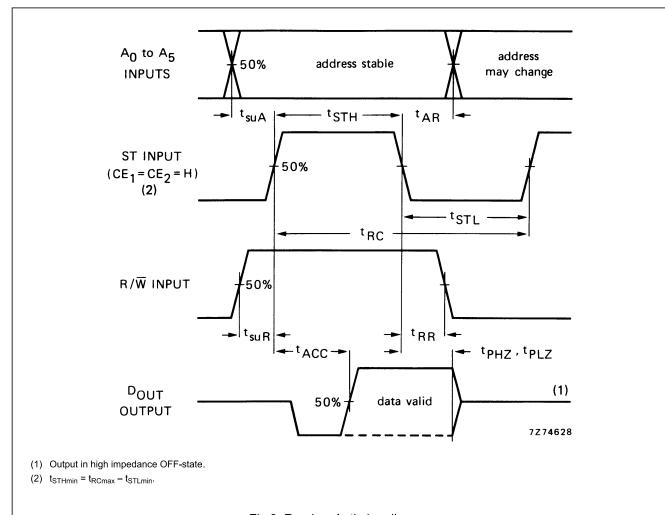
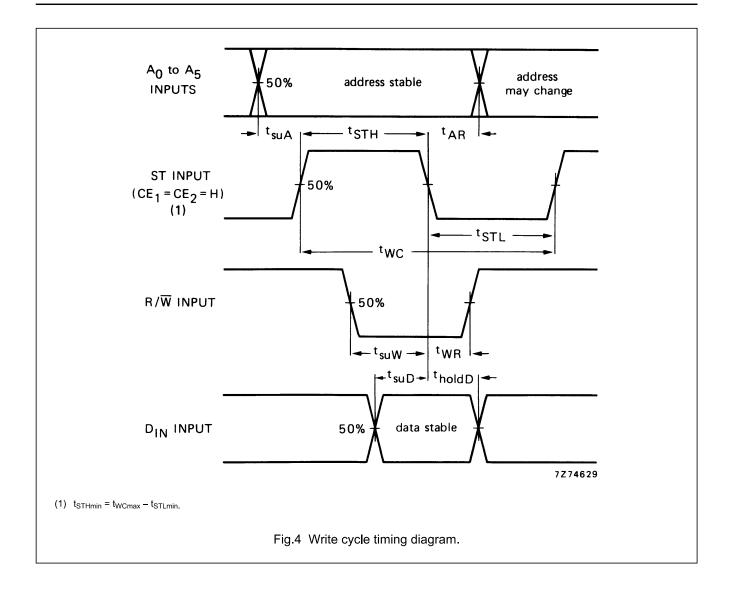


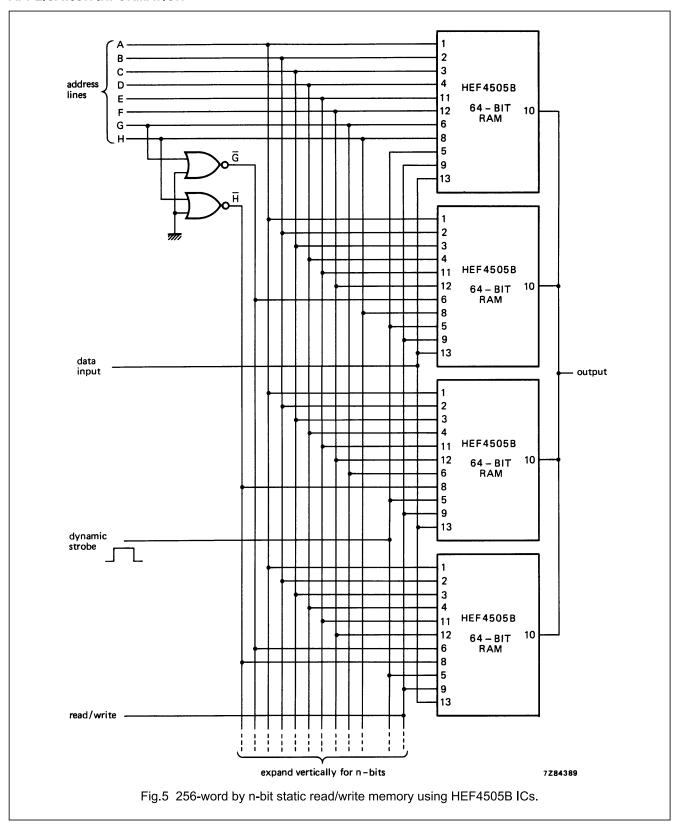
Fig.3 Read cycle timing diagram.

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### **APPLICATION INFORMATION**



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### 64-bit, 1-bit per word random access read/write memory

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Figure 5 shows a 256-word by n-bit static RAM system. The outputs of the four HEF4505B circuits are tied together to form 256 words by 1-bit. Additional bits are attained by paralleling the inputs in groups of four. Memories of larger words can be attained by decoding the most significant bits of the address and AND-ing them with the strobe input.

Fan-in and fan-out of the memory are limited only by speed requirements. The extremely low input and output leakage currents keep the output voltage levels from changing significantly as more outputs are tied together. With the output levels independent of fan-out, most of the power supply range is available as logic swing, regardless of the number of units wired together. As a result, high noise immunity is maintained under all conditions.

The memory system shown in Fig.5 can be interfaced directly with other ICs of the LOCMOS HE family. No external components are required.

Non-volatile information storage is allowed due to very low power dissipation when the memory is powered by a small standby battery. Figure 6 shows an optional standby power supply circuit for making a LOCMOS memory 'non-volatile'. When the usual power fails, a battery is used to sustain operation or maintain stored information. While normal power supply voltage is present, the battery is trickle-charged through a resistor (R) which sets the charging rate. In Fig.6 the sustaining voltage is  $V_B$ , and +  $V_B$  is the ordinary voltage from a power supply.  $V_{DD}$  is connected to the power supply pin of the memory. Low-leakage diodes are recommended to conserve battery power.

